

RFMA7090-0.5W-Q7

UPDATED: 04/24/2008

7.0 - 9.0 GHz High Gain Surface-Mounted PA

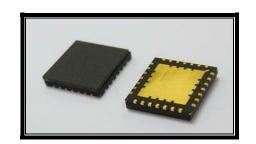
FEATURES

- 7.0 9.0GHz Operating Frequency Range
- 27.0dBm Output Power @1dB Compression
- 34.0dB Typical Power Gain @1dB Compression
- -41dBc OIMD3 @Pout 17dBm/tone
- 7X7mm QFN Package

APPLICATIONS

- Point-to-point and point-to-multipoint radio
- Military Radar Systems

ELECTRICAL CHARACTERISTICS (T_B=25 °C)



SYMBOL	PARAMETER/TEST CONDITIONS	MIN	TYP	MAX	UNITS
F	Operating Frequency Range	7.0		9.0	GHz
P _{1dB}	Output Power @1dB Gain Compression	26.0	27.0		dBm
G _{1dB}	Gain @1dB Gain Compression	30.0	34.0		dB
OIMD3	Output 3 rd Order Intermodulation Distortion @∆f=10MHz, Pout = 17dBm/tone		-41	-38	dBc
Input RL	Input Return Loss		-10	-8	dB
Output RL	Output Return Loss		-5		dB
I _{D1}	Drain Current ¹		200	230	mA
I _{D2}	Drain Current ¹		400	460	mA
V_{D1}, V_{D2}	Drain Voltage		7	8	V
V_{G1}, V_{G2}	Gate Voltage	-2.5		-0.25	V
Rth	Thermal Resistance ²		13		°C/W
Tb	Operating Base Plate Temperature	-30		+80	°C

^{1.} Recommended to bias each amplifier stage separately using a gate voltage range, starting from -2.5 to -0.3V to achieve typical current levels. 2. Rth is mounting dependent. Measured result when used with Excelics recommended evaluation board. **MAXIMUM RATINGS AT 25°C**^{3,4}

SYMBOL	CHARACTERISTIC	ABSOLUTE	CONTINOUS
V_{D1}, V_{D2}	Drain to Source Voltage	12V	8 V
V_{G1}, V_{G2}	Gate to Source Voltage	-5V	-2.5 V
I_{D1}, I_{D2}	Drain Current	ldss	230, 460mA
P_{IN}	Input Power	20dBm	@ 3dB compression
T _{CH}	Channel Temperature	175°C	150°C
T_{STG}	Storage Temperature	-65/175°C	-65/150°C
P_{T}	Total Power Dissipation	8.8W	7.4W

^{3.} Operation beyond absolute or continuous ratings may result in permanent damage or reduction of MTTF respectively.

^{4.} Bias conditions must also satisfy the following equation $V_{DS}^{\star}I_{DS} < (T_{CH} - T_B)/R_{TH}$; where T_B = Temperature of Base Plate

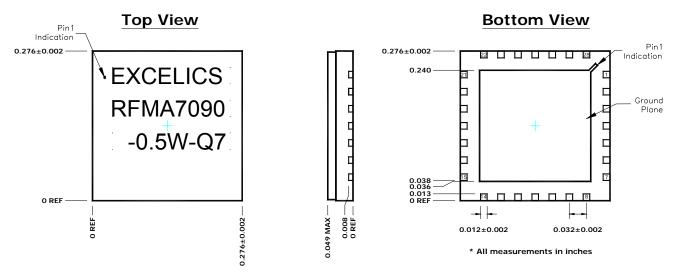


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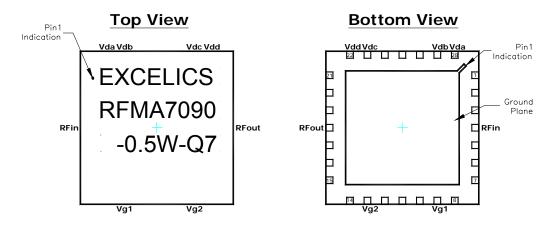
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Package Dimension and Pin Assignment



Additional Notes:

- 1) Ground Plane must be soldered to PCB RF ground
- 2) All dimensions are in inches
- 3) Refer to Excelics application notes on QFNs for further guidelines
- 4) Pin Assignment:



Pin	Assignment	
1, 2, 3, 5, 6, 7, 8, 10, 11, 12, 14	NC	
4	RF_in	
9	V_{g1}	
13	V_{g2}	
15, 16, 17, 19, 20, 21, 22, 24, 25, 26, 28	NC	
18	RF_out	
22, 23	V_{dd}, V_{dc}	
27, 28	V_{db} , V_{da}	

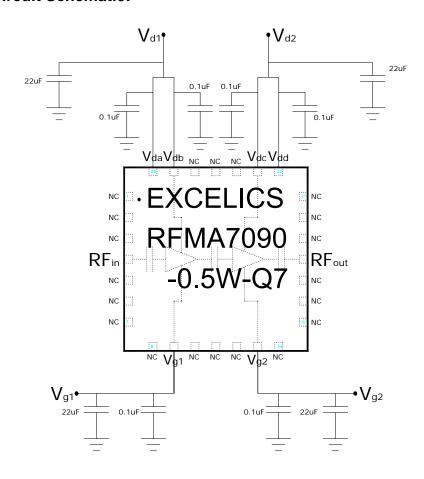


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Recommended Circuit Schematic:



Notes:

- 1) External bypass capacitors should be placed as close to the package as possible.
- 2) Dual biasing sequence required:
 - a. Turn-on Sequence: Apply $V_{g1} = -2.5V$, $V_{g2} = -2.5V$, followed by $V_{d1} = V_{d2} = 7V$, lastly increase $V_{g1} \& V_{g2}$ in sequence until required I_{d1} and I_{d2} is obtained.
 - b. Turn-off Sequence: Turn off V_{d1} & V_{d2} , followed by V_{g1} & V_{g2}
- 3) Demonstration board available upon request.

